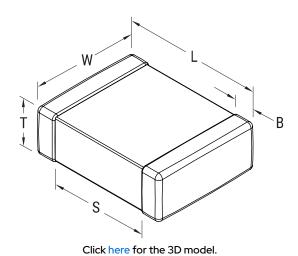


C1206X332F2TACTU

Aliases (C1206X332F2TAC7800)

SMD Comm X8G HT150C Flex, Ceramic, 3,300 pF, 1%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1206, 1.5 mm



General Information	
Series	SMD Comm X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	15 mg
Shelf Life	78 Weeks
MSL	1

3,300 pF

Time is 1000 Hours

100 GOhms

Dimensions	
Chip Size	1206
L	3.3mm +/-0.4mm
W	1.6mm +/-0.35mm
Т	0.78mm +/-0.20mm
S	1.5mm MIN
В	0.6mm +/-0.25mm

3mm +/-0.4mm	Measurement Condition	1 kHz 1.0Vrms
5mm +/-0.35mm	Tolerance	1%
78mm +/-0.20mm	Voltage DC	200 VDC
5mm MIN	Dielectric Withstanding Voltage	500 VDC
6mm +/-0.25mm	Temperature Range	-55/+150°C
	Temp. Coefficient	X8G
&R, 180mm, Plastic Tape	Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
000	Dissipation Factor	0.1% 1 kHz 1.0Vrms
	Aging Rate	0% Loss/Decade Hour: Referee

Insulation Resistance

Specifications

Capacitance

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	4000

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